

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:)
Gunther et al.)
Serial No.: 10/821,292)
Filed: April 9, 2004)
For: Methods and Apparatus for Thermal Management of an Integrated Circuit Die)
Examiner: Tung S. Lau)
Group Art Unit: 2863)
Docket No.: P4728XD)
)

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT UNDER 37 C.F.R. § 1.312

Sir:

This amendment is submitted in accordance with 37 C.F.R. § 1.312 after receipt of a Notice of Allowance.

INTRODUCTORY COMMENTS

This amendment is being submitted after the Notice of Allowance, which was mailed on November 26, 2004. Further, this amendment is being submitted before payment of the issue fee.

Applicants propose herein to amend the specification to recite the patent number of the parent application.

Applicants also submit herewith a copy of an Information Disclosure Statement filed on April 9, 2004, as well as copies of six non-patent documents listed on this Information Disclosure Statement.